

Patent
Docket No: 55259US005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Okada and Uchiya

Group Art Unit: 1711

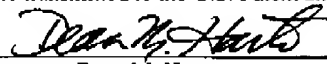
Serial No.: 09/719,893

Filed: 19 December 2000

Examiner: Melanie D. Bissett

For: Heat Conductive Sheet And Method Of Producing The Sheet

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CERTIFICATE OF TRANSMISSION	
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June 13, 2002	
Date	Signature: Dean M. Harts

AMENDMENT UNDER 37 C.F.R. 1.111Commissioner for Patents
Washington, DC 20231

Dear Sir:

In response to the outstanding Official Action dated February 13, 2002, please amend the application as follows:

In the Specification:

On page 6, please delete the paragraph starting on line 15 and ending on line 16.

Please replace the paragraph on page 19 beginning on line 4 and ending on line 8 with the following amended paragraph:

To evaluate the handling property of the heat conductive sheet, the heat conductive sheet was fitted as a heat transfer sheet between an LSI chip and heat radiation fins in an LSI device. The heat conductive sheet could be fitted easily and reliably without any problems such as wrinkles, rupture, fitting mistakes, and so forth.

A version marked up to show changes made to the specification relative to the previous version of the specification is attached.

In the Claims:

Please amend claims 1, 5 and 10 as follows:

1. (First Amendment) A heat conductive sheet including a substrate having a thickness from 1 to 12 μm and a heat conductive resin layer applied to at least one surface of